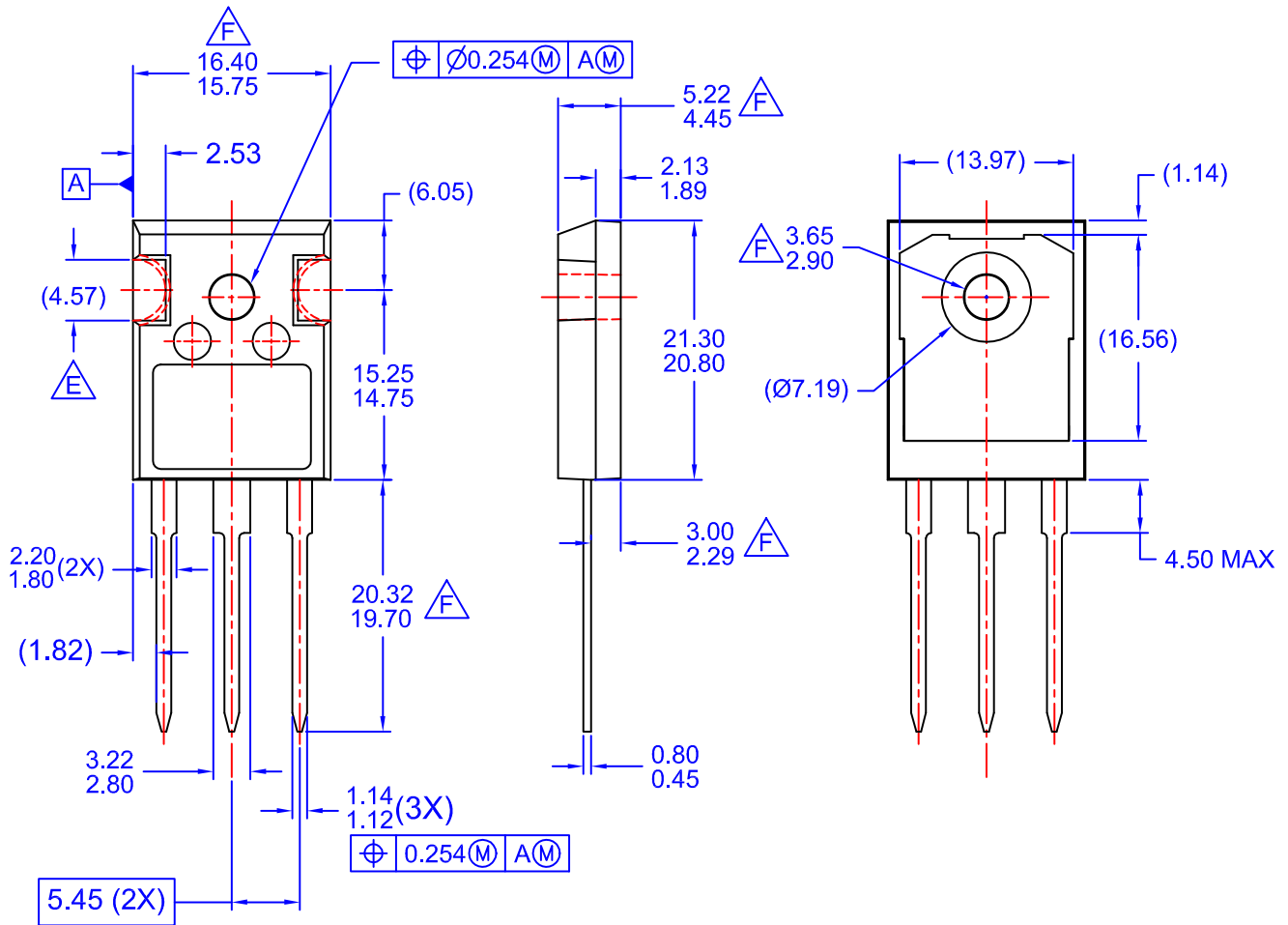




MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS


TO-247-3LD
CASE 340CC
ISSUE O

DATE 31 OCT 2016



- NOTES: UNLESS OTHERWISE SPECIFIED
- A. PACKAGE REFERENCE: JEDEC TO-247, ISSUE "E", VARIATION AD
 - B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
 - C. ALL DIMENSIONS ARE IN MILLIMETERS.
 - D. DRAWING CONFORMS TO ASME Y14.5 - 1994
-  NOTCH MAY BE SQUARE
-  DOES NOT COMPLY JEDEC STANDARD VALUE.

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DESCRIPTION:	TO-247-3LD	PAGE 1 OF 1

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